



# Product End-of-Life Disassembly Instructions

Product Category: Scanners

Marketing Name / Model

[List multiple models if applicable.]

HP Scanjet Enterprise Flow 5000 s3 / L2751A

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm Main board, control panel board, CIS transfer board	3
Batteries	All types including standard alkaline and lithium coin or button style batteries	0
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		439
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords	USB cable, power cord	2
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0

Components, parts and materials containing radioactive substances		0
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## 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Philips Screwdriver	No.2
Tweezers	
Plastic Stick	

## 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Open the rotatable input tray cover. Remove the input tray cover from the top module of the machine.
2. Disassemble the chassis.
3. Pull out the output tray and remove it from the bottom of the machine.
4. Disassemble the top main upper path. Loosen the screws of the top cover module with No.2 Philips screwdriver. Remove the top cover and then the retard roller cover. Remove the screw and then the cables. Remove the springs and cables from CIS module. Remove the flat cable with tweezers. Remove all cables on the transfer board. 4-3) Remove the motor and the door latch. Remove the CIS cover and CIS module. Disassemble the driver module.
5. Loosen the 2pcs of screws from bottom ultrasonic shield with No.2 Philips screwdriver. Remove the bottom frame, transfer board, roller, and roller cover. Loosen the screws from the bottom main paper path. Remove the bottom paper path cover and shield cover with plastic stick and No.2 Philips screwdriver.
6. After the bottom cover removed, remove the left and right trim covers. Disassemble the main board cover with No.2 Philips screwdriver. Pull out the cables.
- 7.
- 8.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

Please refer to the below "Vail Plus Dis-ass'y Tree".

# VAIL PLUS DIS-ASSEMBLY TREE



